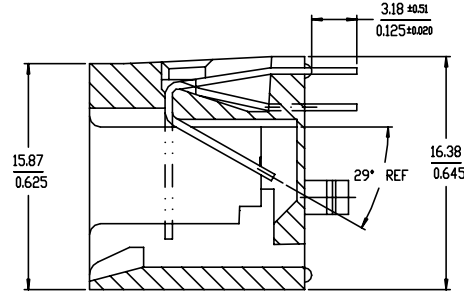
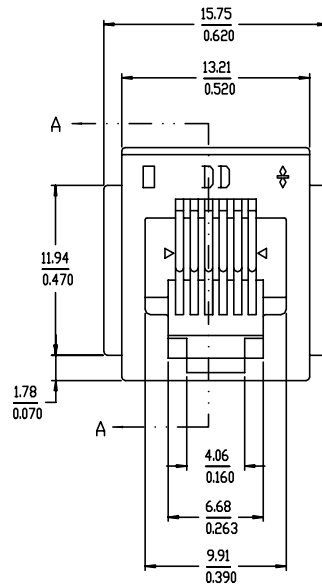
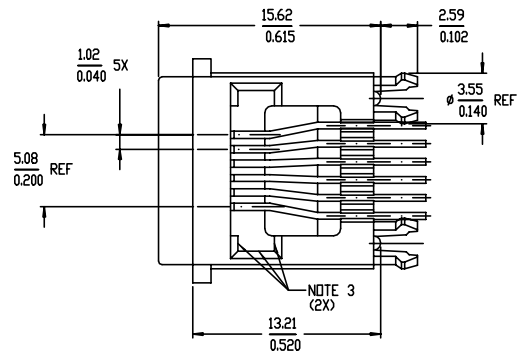
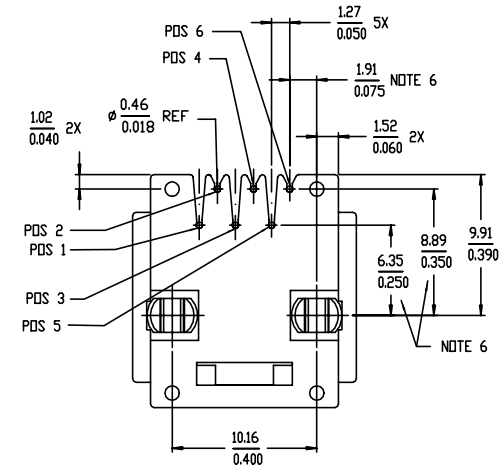


PRODUCT NO.
SEE CHART

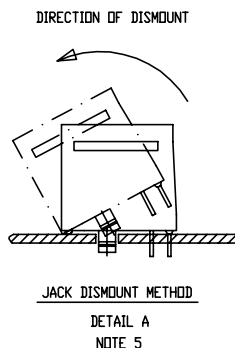
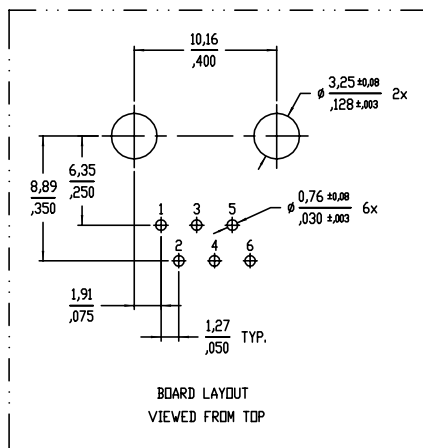


SECTION A-A



mat'l. code				surface ISO1302 ✓		tolerance ISO1101 ISO406		projection 		product family MOD JACK			
ltr ecn nodr				date		tolerances unless otherwise specified		mm 		title			
N	N04-0102	YS	11/23/04	angle line 0°±2'	0.X±0.3				6 POS VERT. SNAP PEG				
P	N08-0097	SH	09/25/08		0.XX±0.15				PCB III MOD JACK ASSY				
R	N08-0170	SH	10/10/08		0.XXX±0.05				scale 2.0				
S	ELX-N-010713	SH	MM 3/14/12										
				dr	M CHENG	7/13/01			dwg no		sheet 1 of 2	size A4	
				enr	M CHENG	7/13/01			90512				
				chr	M CHENG	7/18/01							
				appd	J HSIA	7/20/01							
sheet		revisions		S	S				type		Product Customer Drawing		
index		sheet		1	2								

PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	NOTES
90512-001 -001LF -011LF	ALL	5u" Au + high performance lubricant	BLACK
-002 -002LF -012LF	ALL	5u" Au + high performance lubricant	BLACK
-003 -003LF -013LF	2,3,4,5	5u" Au + high performance lubricant	BLACK
-004 -004LF -014LF	2,3,4,5	50u" / 127u GXT	BLACK
-005 -005LF -015LF	3,4	5u" Au + high performance lubricant	BLACK
-006 -006LF	ALL	5u" Au + high performance lubricant	GREY
-007 -007LF	ALL	5u" Au + high performance lubricant	GREY
-008 -008LF	3,4	5u" Au + high performance lubricant	GREY



PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	REMARKS
90512-101 -101LF -111LF	ALL	5u" Au + high performance lubricant	NOT TOOLED
-102 -102LF -112LF	ALL	5u" Au + high performance lubricant	NOT TOOLED
-103 -103LF -113LF	2,3,4,5	5u" Au + high performance lubricant	NOT TOOLED
-104 -104LF -114LF	2,3,4,5	50u" / 127u GXT	NOT TOOLED
-105 -105LF -115LF	3,4	5u" Au + high performance lubricant	NOT TOOLED

LEAD FREE PRODUCT NO.

0: MEETS WAVE SOLDER PROCESS PRODUCT NO.

1: MEETS PIP PROCESS PRODUCT NO.

NOTES :

- P/NO WITH DASH 0XX -NORMAL WAVE SOLDERING APPLICATION.
P/NO WITH DASH 1XX -IR REFLOW APPLICATION (NOT TOOLED).
- PACKAGING SPEC. BUS-14-164.
- SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- JACK IS FOR 1,57/.062 THICK PCB.
- SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB, PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.
- THESE DIMENSIONS ARE TAKEN FROM THE TOP OF THE PEG.
- THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
- IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.
- EQUIVALENT THICKNESS Au AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTOMER.

mat'l. code				surface	tolerance	projection	product family
				ISO1302	ISO1101 ISO406		MOD JACK
l	tr	ec	n	no	dr	date	tolerances unless otherwise specified
N	N04-0102	YS	11/23/04	angle	0.X±0.3	mm	6 POS VERT. SNAP PEG
P	N08-0097	SH	09/25/08	0°±2°	0.XX±0.15	scale 2.0	PCB III MOD JACK ASSY
R	N08-0170	SH	10/10/08	dr	0.XXX±0.05		
S	ELX-N-010713	SH	3/14/12	enr	M CHENG	7/13/01	dwg no
				chr	M CHENG	7/13/01	sheet 2 of 2
				appd	J HSIA	7/20/01	size
sheet	revision						90512
index	sheet						A4
							type
							Product Customer Drawing